














PREPARATION METHOD

COPPER AND COPPER BASED ALLOYS

 CUTTING		Equipment QATM Qcut / Brillant	Consumable Cut-off wheel: corundum, resin bond Anti-corrosion coolant				
 MOUNTING		Equipment QATM Qpress / Opal	Consumable Bakelite red/black, Thermoplast KEM 20, KEM 30 Hot mounting preferred			Method Hot mounting Cold mounting	
 GRINDING/ POLISHING		Equipment QATM Qpol / Saphir Sample size \varnothing 40 mm					
STEP	MEDIUM		 rpm		 N	 min	
 Planar grinding	SiC-paper/foil P320 (280)	H ₂ O	250-300	▶▶ Synchronous rotation	30	Until plane	
 Pre-polishing	BETA	Dia Complete Poly, 9 μ m	120-150	▶▶ Synchronous rotation	30	3:00-4:00	
 Polishing	SIGMA	Dia Complete Poly, 3 μ m	120-150	▶▶ Synchronous rotation	30	3:00-4:00	
 Final polishing	OMEGA	Eposil F, 0.1 μ m*	120-150	◀▶ Counter rotation	15	1:00-2:00* (H ₂ O during final 0:30)	
 Optional: Etching (chemical)	Cu Etchant A (chloride version)					Approx. 0:02	

* 50 ml Eposil F + 1 ml H₂O₂ + 1 ml NH₃, otherwise polishing time x2